

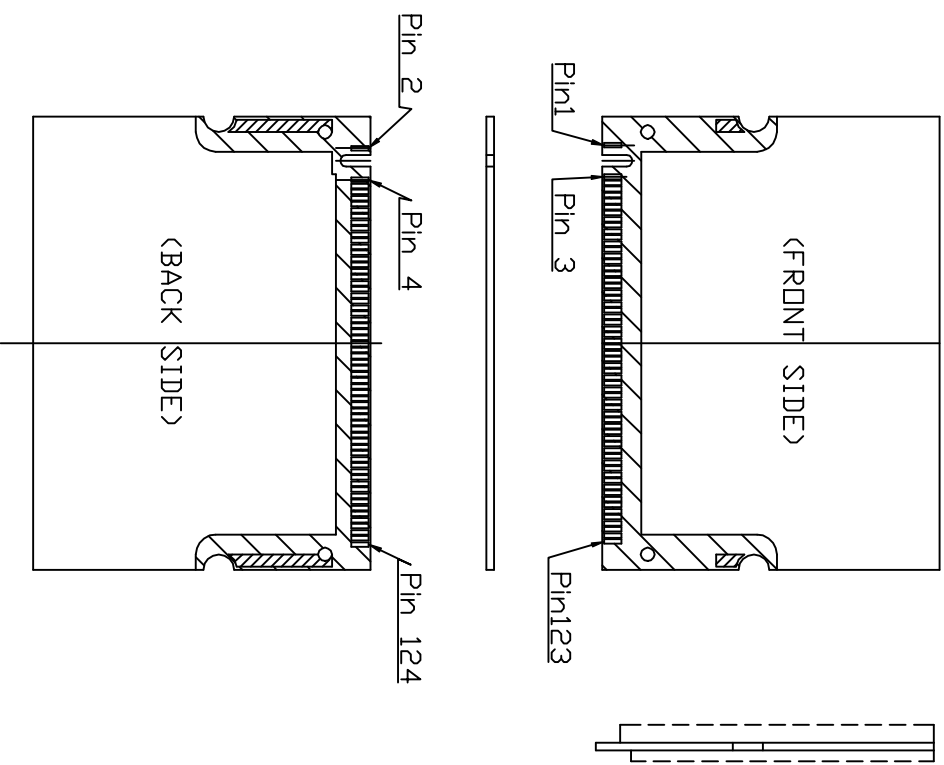
SCLAE 3 : 1

PH=0.80 124POS H=4.0

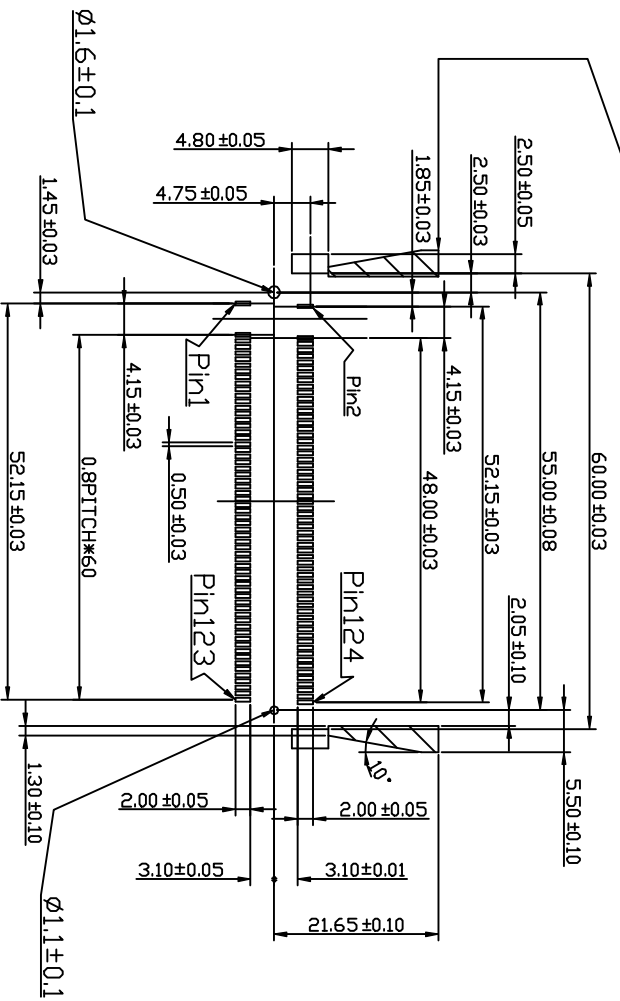
MATERIAL:
 CONTACT: PHOS-BRONZE
 HOUSING: LCP UL94V-0
 COLOR:BLACK
 PLATING:
 CONTACT AREA: GLOD PLATED
 GOLD ON SOLDER AREA
 40U" NICKEL UNDER PLATED FOR
 ENTIRE CONTACT

X.±	X.±	DRN	PRODUCT	MINI-PCI-201
X± 0.2, X±	CHKD		NAME	
XXX 0.1	APPRD		PRODUCT	20251-310
XXX±	MATE		SCALE	2.5:1
3RD			REV	
UNIT	MM		SHEET	

SINGATRON ENTERPRISE CO., LTD. (U.S.A.)



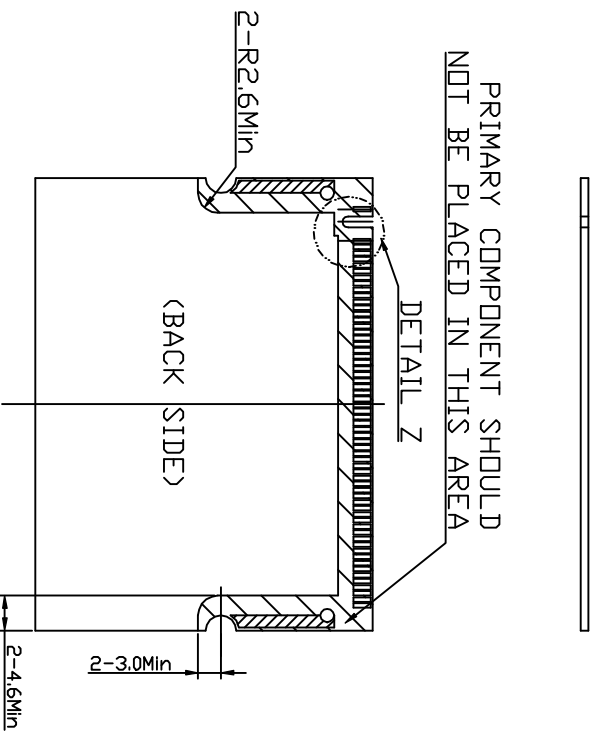
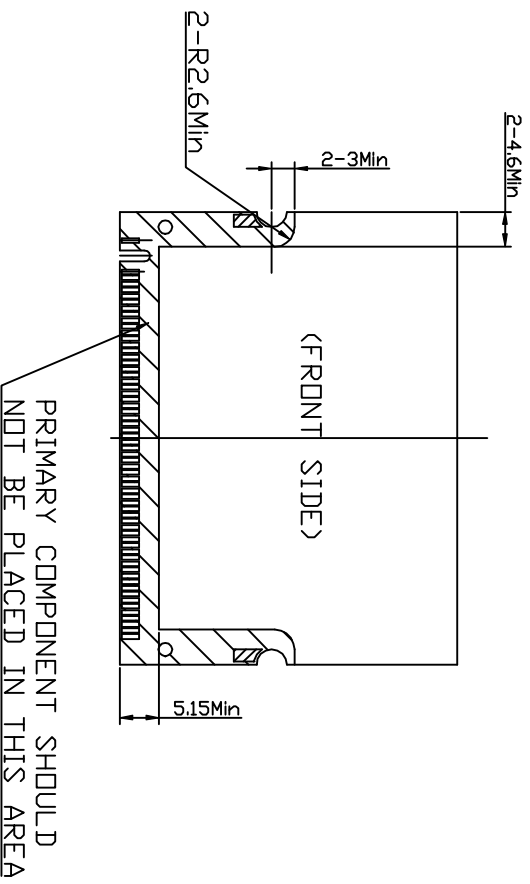
CIRCUIT POSITION OF S.O.DIMM



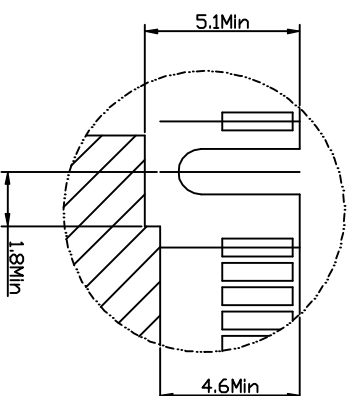
NO COMPONENT AREA
LEVER MOVING AREA
ACCEPT CIRCUIT PATTERN

RECOMMENDED P.C.BOARD PATTERN LAYOUT
<CONNECTOR MOUNTING SIDE>

X.±	X.±	DRN	PRODUCT NAME	MINI-PCI-LAVEROUT
.X± 0.2, X.±	CHKD		PRODUCT NO	
.XX± 0.1	APPRD		REV	
.XXX±	MATE	SCALE 2:1	REV	SHEET
3RD UNIT	MM	SINGATRON ENTERPRISE CO., LTD. (U.S.A.)		

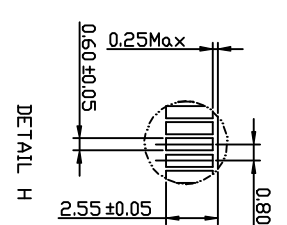
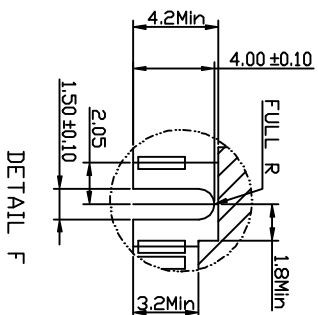
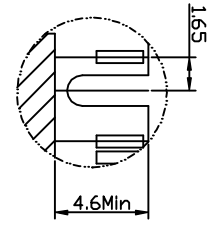
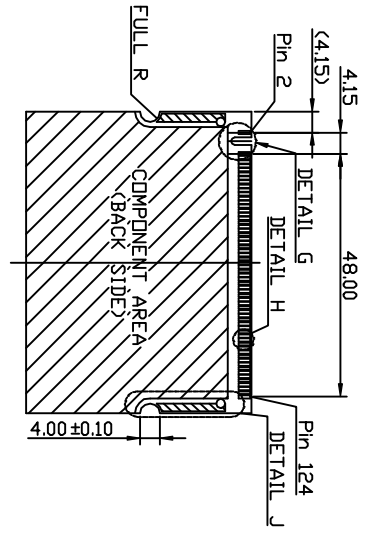
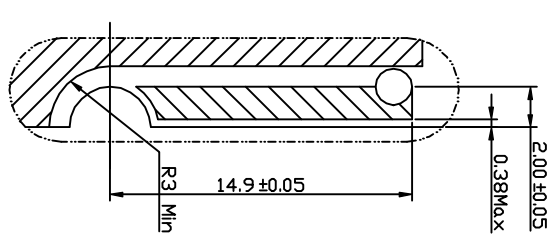
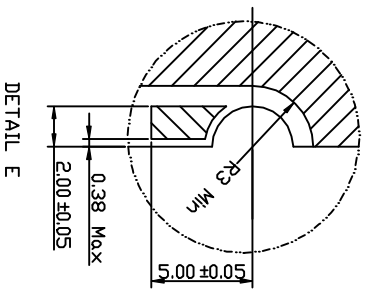
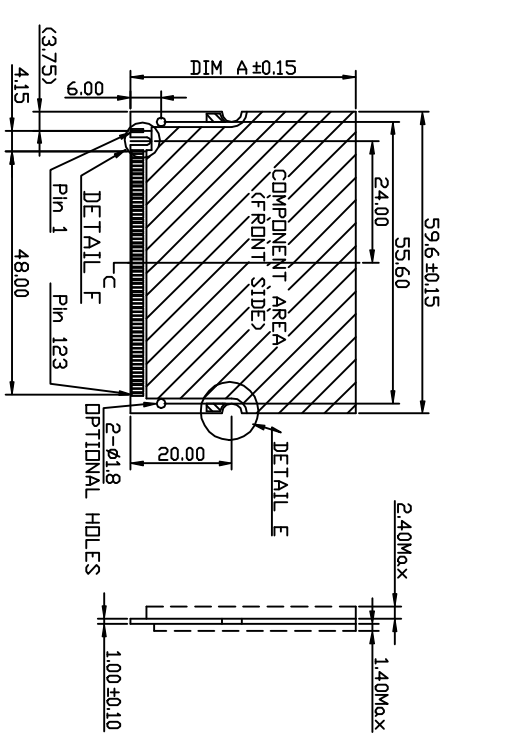


- NOTES:
- MATERIAL:
1-1 HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0
1-2 CONTACT: PHOS-BRZ
COLOR: BLACK
 - FINISH:
2-1 CONTACT AREA: GOLD FLASH DN 40 U MIN. ALL OVER NICKEL
2-2 LOCK LEVER: STAINLESS
2-3 SOLDERING TAB: 120 U SnPb 90/10 DN 40 U ALL OVER NICKEL UNDERPLATED
 - CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION



DETAIL Z

X.±	X.±	DRN		PRODUCT NAME	MINI-PCI-LAVEROUT
.X± 0.2, X.±	CHKD			PRODUCT NO	
.XXX± 0.1	APPRD				
.XXX±	MATE	SCALE	2:1	REV	SHEET
3RD UNIT	MM	SINGATRON ENTERPRISE CO., LTD. (U.S.A.)			



X:±	X:±	DRN	PRODUCT	MINI-PCI-LAVEROUT
.X± 0.2 .X±	CHKD		NAME	
.XXX± 0.1	APPRD		PRODUCT	
.XXX±	MATE	SCALE	2:1	REV
3RD				SHEET
UNIT	MM	SINGATRON ENTERPRISE CO., LTD. (U.S.A.)		